

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5183480

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
LAWRENCE ADVANCED SEMICONDUCTOR TECHNOLOGIES, LLC	09/27/2018
RECEIVING PARTY DATA	
Name:	GES ASSOCIATES L.L.C.
Street Address:	3757 E. BROADWAY ROAD, SUITE 2
City:	PHOENIX
State/Country:	ARIZONA
Postal Code:	85040
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13193498
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	602-904-5402
Email:	LLetham@LethamLF.com
Correspondent Name:	D. LAWRENCE LETHAM
Address Line 1:	9855 E. SOUTHERN AVENUE #51390
Address Line 4:	MESA, ARIZONA 85208
ATTORNEY DOCKET NUMBER:	1805.102.030
NAME OF SUBMITTER:	D. LAWRENCE LETHAM
SIGNATURE:	/D. Lawrence Letham/
DATE SIGNED:	10/11/2018
Total Attachments: 4	
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ASSIGNMENT OF INVENTIONS AND INTELLECTUAL PROPERTY

This ASSIGNMENT, effective as of September 27, 2018 ("Effective Date"), is made and entered into by and between Lawrence Semiconductor Investments, Inc., an Arizona corporation, and Lawrence Advanced Semiconductor Technologies, LLC, an Arizona limited liability company (both referred to herein as ASSIGNOR), both with offices at 2300 West Huntington Drive, Tempe, Arizona, 85282, and GES Associates L.L.C., an Arizona limited liability company (hereinafter referred to as ASSIGNEE), an Arizona limited liability company, with offices at 3757 E. Broadway Road, Suite 2, Phoenix, Arizona, 85040;

WHEREAS, ASSIGNOR has acquired all right, title and interest in and to the patent applications and patents identified in Table 1, attached hereto, and the inventions or improvements disclosed therein ("Assigned Property");

WHEREAS, ASSIGNEE is desirous of acquiring ASSIGNOR's entire right, title and interest in and to the Assigned Property including the rights to sue for and/or collect damages for infringement committed before the Effective Date of this ASSIGNMENT;

NOW THEREFORE, for and in consideration of the promises and mutual covenants herein contained, the parties hereto agree as follows:

In consideration for the payment of US\$ 1.00 and other good and valuable consideration, receipt of which is hereby acknowledged, ASSIGNOR hereby assigns and transfers to ASSIGNEE all right, title and interest worldwide in and to the Assigned Property including the rights to sue for and/or collect damages for infringement committed before the Effective Date of this ASSIGNMENT. This ASSIGNMENT and transfer of right, title and interest includes the rights to file and obtain United States and foreign patents in any country, inventor's certificates and utility models, and all divisions, reissues, substitutions, reexaminations, and continuations thereof, the rights to sue for past infringement, and the rights to collect damages for past infringement.

This ASSIGNMENT was negotiated and executed voluntarily and is not the result of duress, fraud, undue influence or threat of any kind. The parties had the opportunity to read and consider this ASSIGNMENT, to consult with counsel, and fully understand this ASSIGNMENT.

ASSIGNOR represents and warrants to ASSIGNEE that ASSIGNOR owns all right, title and interest worldwide in and to the Assigned Property. ASSIGNOR represents and warrants to ASSIGNEE that ASSIGNOR may execute this ASSIGNMENT without violating its charter and organizational documents, any resolution of its governing board or owners or any other agreement to which the ASSIGNOR is a party.

ASSIGNOR agrees to provide all assistance reasonably requested by ASSIGNEE, at ASSIGNEE's expense, in the establishment, registration, maintenance, preservation and enforcement of ASSIGNEE's rights in or to the Assigned Property.

ASSIGNOR affirms to ASSIGNEE, its successors and assigns, that the rights and

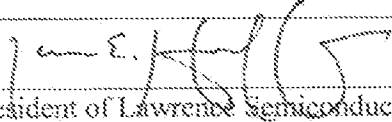
property herein conveyed are free and clear of any encumbrance, and that ASSIGNOR has full rights to convey the Assigned Property.

Any signatory to this ASSIGNMENT warrants and acknowledges that they have the full right and authority to enter into this ASSIGNMENT and are authorized to execute this ASSIGNMENT on behalf of the entity for which they sign.

This ASSIGNMENT may be executed in counterparts, each of which shall constitute an original, but both of which, when taken together, will constitute the same instrument.

IN WITNESS WHEREOF, the ASSIGNOR and ASSIGNEE have executed this ASSIGNMENT by signing below.

Lawrence Semiconductor Investments, Inc.; and
Lawrence Advanced Semiconductor Technologies, LLC (ASSIGNOR)

Printed Name:	James E. Huffman
Signature:	
Position:	President of Lawrence Semiconductor Investments, Inc.
Date:	10/2/2018

GES Associates L.L.C. (ASSIGNEE)

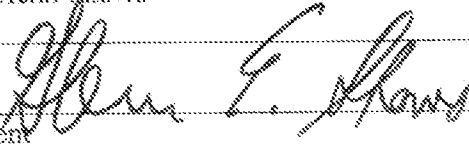
Printed Name:	Glenn Shows
Signature:	
Position:	President
Date:	10/9/18

Table 1: Patent Applications, Patents, Inventions, and Improvements

App/Patent No.	Title	Filing/Issue Date	Docket No.
61/369,047	Substrate Processing Apparatuses and Systems	07/29/2010	LAS-001
61/369,077	Electrical Resistance Heater and Heater Assemblies	07/30/2010	LAS-002
61/369,072	Systems, Apparatuses, and Methods for Chemically processing Substrates Using the Coanda Effect	07/30/2010	LAS-003
61/277,624	Revolutionary Technology for the Production of White LEDs and Solar Cells	09/28/2009	LAS-004
62/353,027	Metering Valve	06/21/2016	LAS-005
13/193,498	Substrate Processing Apparatuses and Systems	07/28/2011	LAS-001US
13/194,945	Electrical Resistance Heater and Heater Assemblies	07/30/2011	LAS-002US
13/194,947	Systems, Apparatuses, and Methods for Chemically processing Substrates Using the Coanda Effect	07/30/2011	LAS-003US
12/890,463	Semiconductor Deposition System and Method	09/24/2010	LAS-004US
PCT/US2011/045796	Substrate Processing Apparatuses and Systems	07/28/2011	LAS-001PCT
PCT/US2011/046058	Electrical Resistance Heater and Heater Assemblies	07/30/2011	LAS-002PCT
PCT/US2011/046059	Systems, Apparatuses, and Methods for Chemically processing Substrates Using the Coanda Effect	07/30/2011	LAS-003PCT
US 6,774,060	Methods and Apparatus for Thermally Processing Wafers	08/10/2004	
US 6,331,212	Methods and Apparatus for Thermally Processing Wafers	12/18/2001	
PCT/US2001/040511	Methods and Apparatus for Thermally Processing Wafers	04/12/2001	
10-2013-7004441	Substrate Processing Apparatuses and Systems	07/28/2011	LAS-001KR
2013-521987; JP6045035	Substrate Processing Apparatuses and Systems		LAS-001JP
201300374-4; SG187111	Substrate Processing Apparatuses and Systems	07/28/2011	LAS-001SG

App/Patent No.	Title	Filing/Issue Date	Docket No.
201220365; TW1590308	Substrate Processing Apparatuses and Systems	07/28/2011	LAS-001TW
100126756	Electrical Resistance Heater and Heater Assemblies	07/28/2011	LAS-002TW
100126763	Systems, Apparatuses, and Methods for Chemically processing Substrates Using the Coanda Effect	07/28/2011	LAS-003TW
EP2559108	Substrate Processing Apparatuses and Systems	07/28/2011	LAS-001EP
	Substrate Processing Apparatuses and Systems. Registration of EP2559108.		LAS-001GB
	Substrate Processing Apparatuses and Systems. Registration of EP2559108.		LAS-001AU
	Substrate Processing Apparatuses and Systems. Registration of EP2559108.		LAS-001PO
	Substrate Processing Apparatuses and Systems. Registration of EP2559108.		LAS0001CZ
	Substrate Processing Apparatuses and Systems. Registration of EP2559108.		LAS0001BE
	Substrate Processing Apparatuses and Systems. Registration of EP2559108.		LAS0001FR
	Substrate Processing Apparatuses and Systems. Registration of EP2559108.		LAS0001GE
	Substrate Processing Apparatuses and Systems. Registration of EP2559108.		LAS0001IT
	Substrate Processing Apparatuses and Systems. Registration of EP2559108.		LAS0001NL

Date format: MM/DD/YYYY